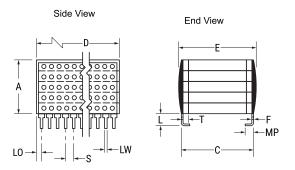


## KPS LDD Comm SMPS, Ceramic, 8.2 uF, 10%, 500 VDC, X7R, N/A



Dimensions		
D	25.715mm +/-1.585mm	
L	1.78mm +/-0.25mm	
Т	1.397mm MAX	
S	2.54mm TYP	
F	0.254mm +/-0.051mm	
A	9.144mm MAX	
С	11.43mm +/-0.635mm	
E	12.7mm MAX	
LO	1.586mm MAX	
LW	0.508mm +/-0.051mm	
MP	1.27mm MIN	

Packaging Specifications		
Packaging:	Waffle, Box	
Packaging Quantity:	28	

General Information	
Series:	KPS LDD Comm SMPS
Style:	Leaded Stacked Chip
Description:	Low ESR, High Current Stacked Ceramic Chips
Features:	Low ESR, High Current, High Performance
RoHS:	No
Prop 65:	warning: Cancer and reproductive harm - www.p65warnings.ca.gov.
SCIP Number:	4221181d-d71c-4d0a- af45-5eab760732b2
Termination:	60/40 Solder Coated
Lead:	J Leads
Failure Rate:	N/A
Testing and Reliability:	Commercial
AEC-Q200:	No
Notes:	Note: Number of chips in stack depends on design. Number of Chips in this stack = 3. Note: Turn Radius For Lead Extension Is 0.1 Radians (Typical). Note: Lead alignment within pin rows shall be within ±.0.13 mm.

Specifications		
Capacitance:	8.2 uF	
Capacitance Tolerance:	10%	
Voltage DC:	500 VDC	
Dielectric Withstanding Voltage:	750 VDC	
Temperature Range:	-55/+125°C	
Temperature Coefficient:	X7R	
Dissipation Factor:	2.5% 1 kHz 25C	
Aging Rate:	3% Loss/Decade Hour	
Insulation Resistance:	12.2 GOhms	

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.



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## >>KEMET(基美)